

Schottky Barrier Diode Silicon Epitaxial

1SS413CT

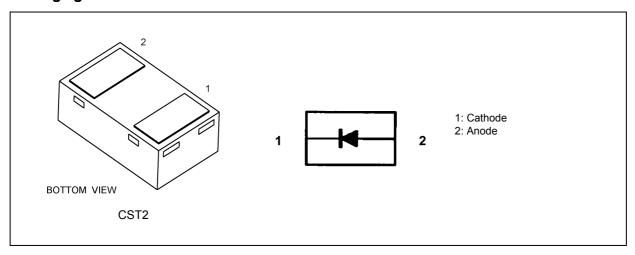
1. Applications

· High-Speed Switching

2. Features

(1) Low forward voltage : $V_{F(3)} = 0.50 \text{ V (typ.)}$ (2) Low reverse current : $I_R = 0.5 \mu\text{A (max)}$ (3) Small total capacitance : $C_t = 3.9 \mu\text{F (typ.)}$

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Rating	Unit
Peak reverse voltage	V _{RM}		25	V
Reverse voltage	V _R		20	
Peak forward current	I _{FM}		100	mA
Average rectified current	I _O		50	mA
Power dissipation	P _D	(Note 1)	100	mW
Non-repetitive peak forward surge current	I _{FSM}	(Note 2)	1	Α
Junction temperature	Tj		125	Ĵ
Storage temperature	T _{stg}		-55 to 125	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on a glass epoxy circuit board of 20 mm \times 20 mm, Pad dimension of 4 mm \times 4 mm.

Note 2: Measured with a 10 ms pulse.

Start of commercial production



5. Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V _{F(1)}	I _F = 1 mA	_	0.33	_	V
Forward voltage	V _{F(2)}	I _F = 5 mA	_	0.38		V
Forward voltage	V _{F(3)}	I _F = 50 mA		0.50	0.55	V
Reverse current	I _R	V _R = 20 V		_	0.5	μА
Total capacitance	Ct	V _R = 0 V, f = 1 MHz	_	3.9		pF

6. Marking

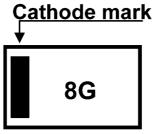
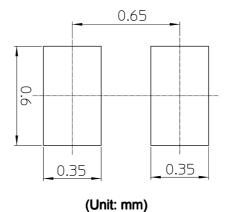


Fig. 6.1 Marking

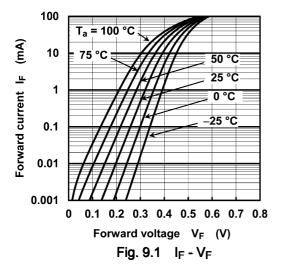
7. Usage Considerations

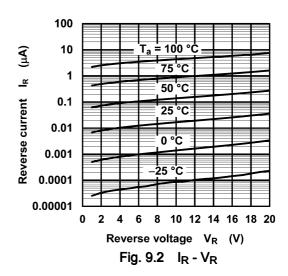
Schottky barrier diodes (SBDs) have reverse leakage greater than other types of diodes. This makes SBDs
more susceptible to thermal runaway under high-temperature and high-voltage conditions. Thus, both
forward and reverse power losses of SBDs should be considered for thermal and safety design.

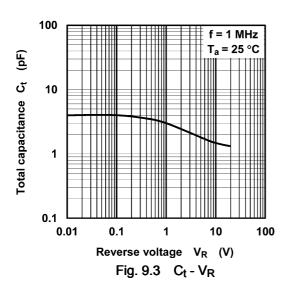
8. Land Pattern Dimensions (for reference only)

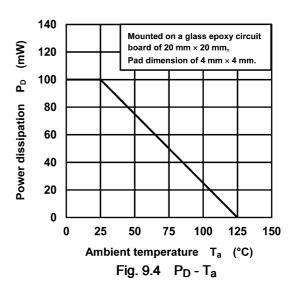


9. Characteristics Curves (Note)







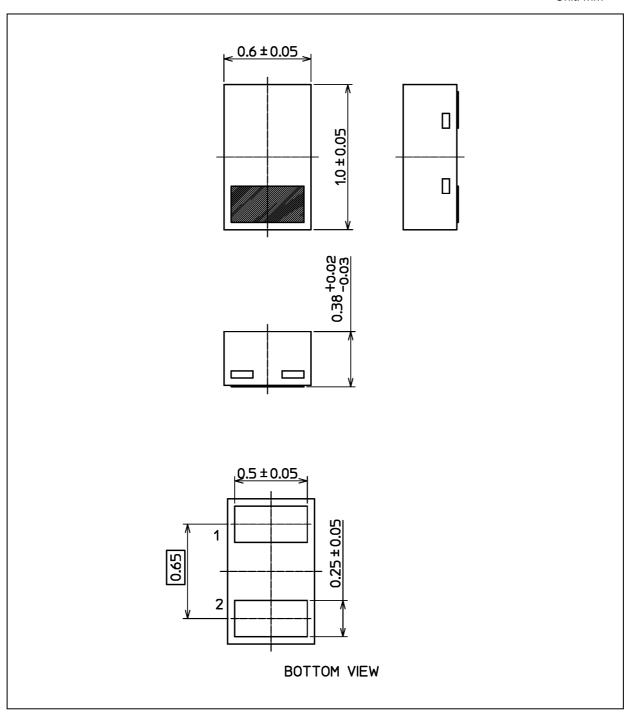


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 0.7 mg (typ.)

	Package Name(s)
TOSHIBA: 1-1P1S	
Nickname: CST2	



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